

*Examiner: Cgs*

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AN 1991-032540 [05] WPIDS  
DNC C1991-014083  
TI Mfg. high purity copper - using copper anode in electrolytic bath  
comprising alkyl-pyridinium halide and cuprous chloride.  
DC L03 M28  
PA (FURU) FURUKAWA ELECTRIC CO LTD  
CYC 1  
PI JP 02301585 A 19901213 (199105)\*  
ADT JP 02301585 A JP 1989-121768 19890516  
PRAI JP 1989-121768 19890516  
AB JP 02301585 A UPAB: 19930928

Claimed is effecting electrolysis by counter facing a Cu-anode which serves as the raw material to a cathode to which the Cu is to be electrodeposited, in an electrolytic bath comprising an alkylpyridinium halide and cuprous chloride obtd. by dummy plating (electrolytic purification) from pure Cu low in Ag or by using an insoluble anode.

The electrolytic bath pref. is an organic bath containing cuprous chloride and an alkylpyridinium halide (e.g., butylpyridinium chloride at a molar ratio of 1/4 to 4/1, and the electrolysis is effected under an inert atmos. at the bath temp of 0 - 150deg C, applying a current at a density of 0.1 - 30 A/dm<sup>2</sup>.

USE/ ADVANTAGE - Provides high purity Cu 99.999 - 99.9999 or even higher, partic. having good electric conductivity as well as low temp softening properties; suitable for use as bonding wire of semiconductor devices, sputtering targets, fine wirings for audio equipments, soft rolled printing circuits, and the like.  
@ (3pp Dwg.No.O/O)

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